



Recent Advances in Smart Materials and Structures

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Message from the Guest Editors

Dear Colleagues,

We are inviting submissions to the Special Issue entitled “Recent Advances in Smart Materials and Structures”.

The application of smart materials and structures is one of the most important issues of the future. To create a more advanced form of materials and structures, it is necessary to provide the required functions of sensing, information converting, automated response, self adaptation and so on. Typically, smart materials can be subdivided based on their response mode or different external stimulus. Therefore, devices based on smart materials and structures can be applied for multi-functional sensors, photoelectric and piezoelectric fields, and so on. In this Special Issue, we invite submissions exploring cutting-edge research and recent advances in the field of smart materials and structures. Both theoretical and experimental studies are welcome, as well as comprehensive review and survey papers.

Keywords

- smart materials
- micro/nano structures
- functional devices
- fabrication method





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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